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May 2015

FQU5N50CTU_WS

N-Channel QFET $^{\rm @}$ MOSFET 500 V, 4.0 A, 1.4 Ω

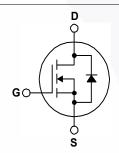
Features

- 4.0 A, 500 V, $R_{DS(on)} = 1.4 \Omega @V_{GS} = 10 V$
- Low Gate Charge (Typ. 18 nC)
- Low Crss (Typ. 15 pF)
- Fast Switching
- 100% Avalanche Tested
- · Improved dv/dt Capability

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQU5N50CTU_WS	Units	
$V_{\rm DSS}$	Drain-Source Voltage		500	V	
D	Drain Current - Continuous (T _C = 25°C)		4.0	Α	
	- Continuous (T _C = 100°C)	2.4	А		
DM	Drain Current - Pulsed	(Note 1)	16	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	300	mJ	
I _{AR}	Avalanche Current	(Note 1)	4	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.8	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
P_{D}	Power Dissipation (T _C = 25°C) - Derate above 25°C		48	W	
			0.38		
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FQU5N50CTU_WS	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	110	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQU5N50CTU_WS	FQU5N50CS	I-PAK	Tube	N/A	N/A	75 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	500			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.5		V/°C
Ines	7 0 1 1/1 5 1 0 1	V _{DS} = 500 V, V _{GS} = 0 V		-	1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 400 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V		-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30 V, V_{DS} = 0 V		1	-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.0 A		1.14	1.4	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 2.0 \text{ A}$		5.2		S
C _{iss}	C Characteristics Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		480	625	pF
C _{oss}	Output Capacitance			80	105	pF
C _{rss}	Reverse Transfer Capacitance			15	20	pF
	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	V 050V/ 5.4		12	35	ns
t _r	Turn-On Rise Time	$V_{DD} = 250 \text{ V}, I_D = 5 \text{ A},$ $V_{GS} = 10 \text{ V}, R_G = 25 \Omega$		46	100	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} - 10 V, R _G - 25 Ω		50	110	ns
t _f	Turn-Off Fall Time	(Note 4)		48	105	ns
Qg	Total Gate Charge	V _{DS} = 400 V, I _D = 5 A,		18	24	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	/	2.2		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		9.7		nC
	ource Diode Characteristics and	Maximum Ratings				ı
- . u∪	Maximum Continuous Drain-Source Diode Forward Current					
I _S	Maximum Continuous Drain-Source Diode	Forward Current			4	Α

Q_{rr} Notes

t_{rr}

 V_{SD}

1. Repetitive rating : pulse width limited by maximum junction temperature.

Drain-Source Diode Forward Voltage

2. L = 21.5 mH, I $_{AS}$ = 5 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 Ω , starting T $_{J}$ = 25°C.

Reverse Recovery Time

Reverse Recovery Charge

- 3. $I_{SD} \le 5$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, starting $T_J = 25$ °C.
- 4. Essentially independent of operating temperature.

ns

μC

1.4

263

(Note 4)

 $V_{GS} = 0 V, I_S = 4 A$

 $V_{GS} = 0 \text{ V}, I_{S} = 5 \text{ A},$

 $dI_F / dt = 100 A/\mu s$

Typical Characteristics

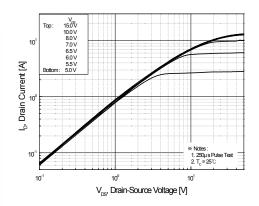


Figure 1. On-Region Characteristics

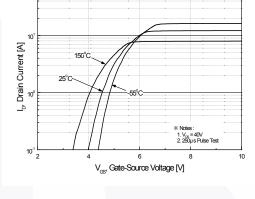


Figure 2. Transfer Characteristics

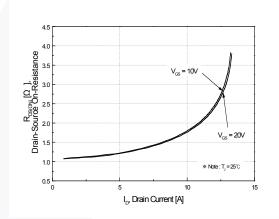


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

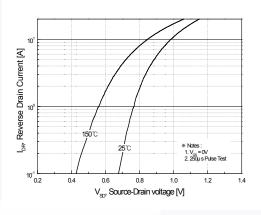


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

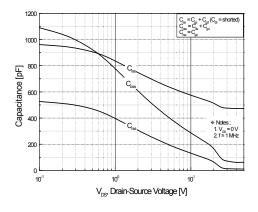


Figure 5. Capacitance Characteristics

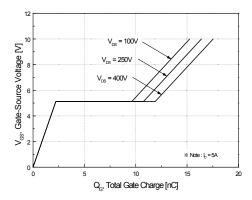


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

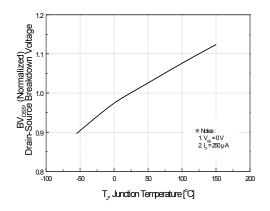


Figure 7. Breakdown Voltage Variation vs Temperature

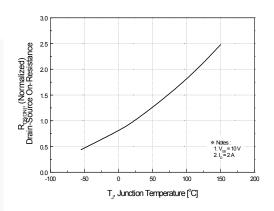


Figure 8. On-Resistance Variation vs Temperature

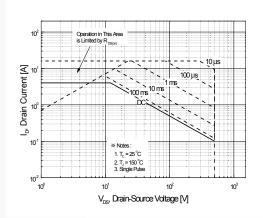


Figure 9. Maximum Safe Operating Area

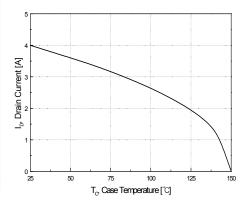


Figure 10. Maximum Drain Current vs Case Temperature

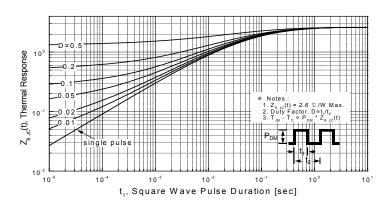


Figure 11. Transient Thermal Response Curve

Figure 12. Gate Charge Test Circuit & Waveform

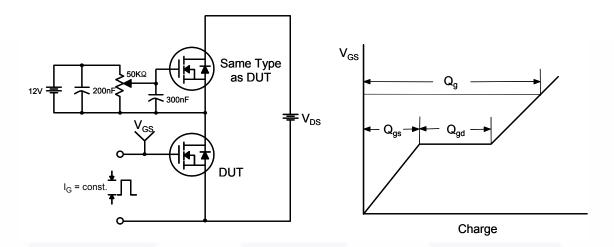


Figure 13. Resistive Switching Test Circuit & Waveforms

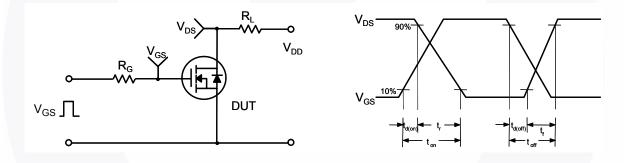
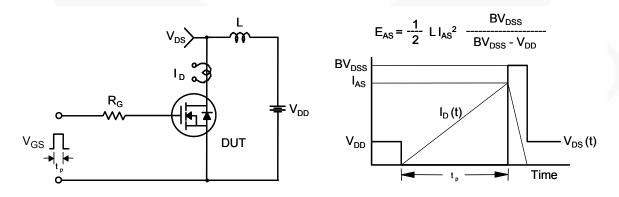


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



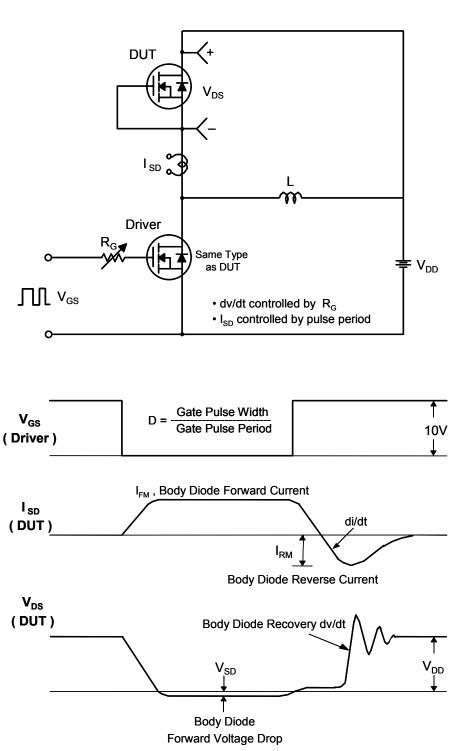
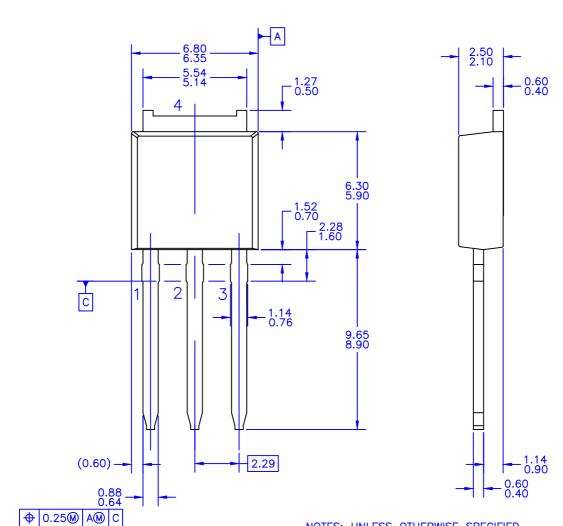
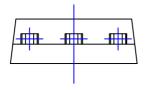


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



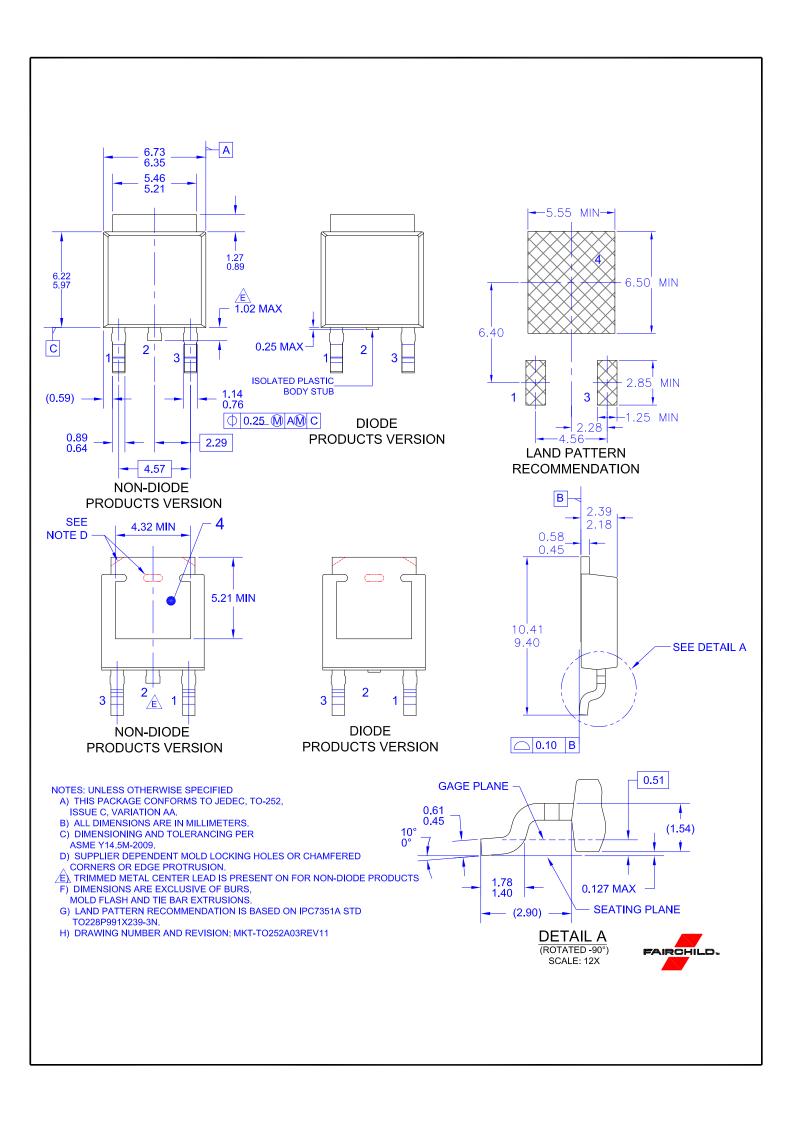


3 PLCS

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Офис по работе с юридическими лицами:

105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru moschip.ru_6 moschip.ru_4 moschip.ru_9